cutting a substrate having a [along said] slice line provided on the substrate and a guide line provided, which corresponds to the slice line and is different from the slice line; and

detecting a position of the guide line and correcting a cutting position while the substrate is cut along the slice line [while correcting a cutting position].

2. (Amended) A method according to claim 1, wherein the [said] guide line is used as a guide line of the [said] slice line and is, thereafter, set ~~to a s~~lice line for cutting.

3. (Amended) A method according to claim 1, wherein the [said] guide line is provided on the substrate and the slice line and the guide line are simultaneously formed [simultaneously with said slice line].

4. (Amended) A substrate cutting method comprising:

cutting a substrate having a slice line provided on the substrate and a guide line provided, which corresponds to the slice line and is different from the slice line; and

detecting a position of the guide line and correcting a cutting position while the substrate is cut along the slice line [method according to claim 1],

wherein the [said] guide line is an electrode line provided on the substrate.

5. (Amended) ~~A method~~ according to claim 1, wherein said detecting step comprises detecting the position [the detection of said position is executed] by using a light source and a photoelectric converting ~~element~~.

6. (Amended) A method according to claim 1, wherein said cutting step is executed by a rotary blade.

7. (Amended) A substrate cutting method comprising:

cutting a substrate having an [method according to claim 1, wherein said slice line and said guide line are formed by] electrode layer [layers] provided on the substrate;

detecting, during the cutting, a position of a guide line provided corresponding to a slice line formed by the electrode layer; and

correcting a cutting position based on the detection in said detecting step.

8. (Amended) A method according to claim 7, wherein the [said] electrode layer is formed by a same material as that of an electrode line formed on the [said] substrate.

9. (Amended) A method according to claim 7, wherein the [said] electrode layer is formed simultaneously with an electrode line formed on the [said] substrate.

10. (Amended) A method according to claim 1, wherein the [said] slice line and the [said] guide line are arranged in parallel.

11. (Amended) A substrate cutting method [whereby when] comprising:

cutting a substrate, provided with [on which] a slice line and a guide line, along the slice line of the substrate;

detecting the guide line during the cutting to detect deviation with respect to the guide line; and

correcting a cutting position based on the detected deviation [are formed is cut along said slice line of said substrate, a misalignment is detected by detecting said guide line upon said cutting and the substrate is cut while correcting said misalignment].

12. (Amended) A method according to claim 11, wherein the [said] slice line and the [said] guide line each comprises an electrode line, which constitutes a [are electrode lines constructing a thin film] semiconductor element formed on the [said] substrate.

13. (Amended) A method according to claim 11, wherein the [said] guide line is commonly used as the [said] slice line.

Please add claims 19 through 22 as follows:

--19. A method according to claim 1, wherein the slice line and the guide line are formed by an electrode layer.